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Application Number: 10/709,968

Application File Date: 6/9/2004

Applicant: Rong Huang

Title: Low Profile Opto-electronic Package

Examiner/GAU: James P. Hughes/2883

AMENDMENT A

U.S. Department of Commerce

Commissioner for Patent

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action mailed 2005 Sept. 7, please amend the above application as follows:

Claims: Cancel all claims of record and substitute new claims 1 to 4 as follows:

[c1]

A package for packaging opto-electric devices, comprising:

a generally rectangular package box comprising four sidewalls, one of said sidewalls having an optical connector;

a generally rectangular platform on which opto-electronic devices and a plurality of optical components to be disposed, which having means for attachment of two sides of said platform to two of said sidewalls;

attachment means for moving vertically and tilting said platform relative to said sidewalls to align said opto-electronic devices to said optical connector optically with the lateral movement of said opto-electronic devices and said optical components on the top of said platform and then securing said platform to said package box by one of solder, epoxy, or welder;

[c2]

The package of claim 1 further comprising two thermal electrical coolers, each comprising a cold junction side and a hot junction side and first having means for fixing of said hot junction side to one surface of said sidewalls and having means for attachment of said cold junction side to one side of said platform;